

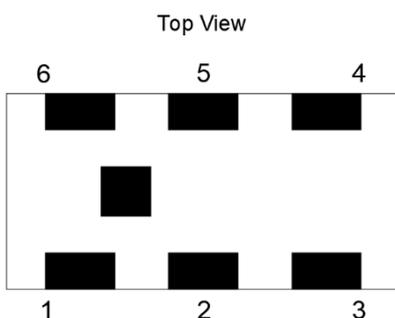
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

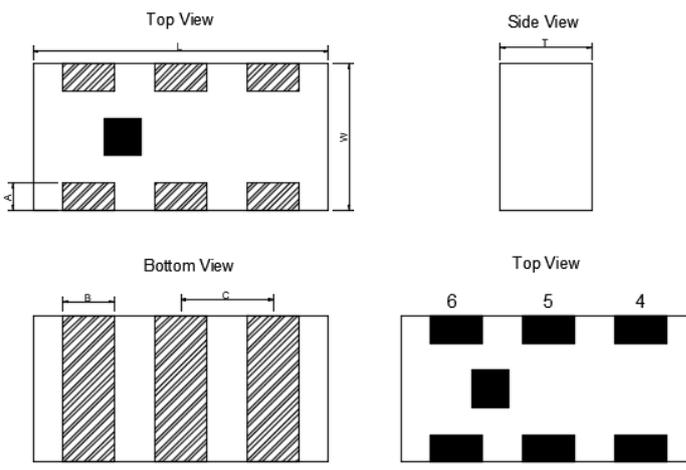
| NO.  | Specification             |                           |                             |
|--|---------------------------|---------------------------|-----------------------------|
| 1  | Frequency range (MHz)     | 300-800 MHz               | 885-2700 MHz                |
| 2  | Insertion Loss (dB) @25°C | 0.6 dB Max. @300-500 MHz  | 1.8 dB Max. @ 885-900 MHz   |
|  |                           | 0.8 dB Max. @500-700 MHz  | 1.5 dB Max. @ 900-1000 MHz  |
|  |                           | 1.0 dB Max. @700-750 MHz  | 0.9 dB Max. @ 1000-2320 MHz |
|  |                           | 2.0 dB Max. @750-800 MHz  | 0.8 dB Max. @2320-2370 MHz  |
|  |                           |                           | 1.2 dB Max. @2370-2700 MHz  |
| 3  | Return Loss (dB)          | 10 Min.                   | 10 Min.                     |
| 4  | Attenuation               | 15 dB Min. @ 885-2700 MHz | 11 dB Min. @ 300-800 MHz    |
| 5  | Impedance ( $\Omega$ )    | 50                        | 50                          |
| 6  | Power(W)                  | 2                         |                             |
| <b>Operating &amp; Storage Condition (Component)</b>                               |                           |                           |                             |
| Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C |                           |                           |                             |
| <b>Storage Condition before Soldering (Included packaging material)</b>            |                           |                           |                             |
| Storage Temperature Range: +5 ~ +40 °C   |                           |                           |                             |
| Humidity: 30 to 70% relative humidity  |                           |                           |                             |

### Construction

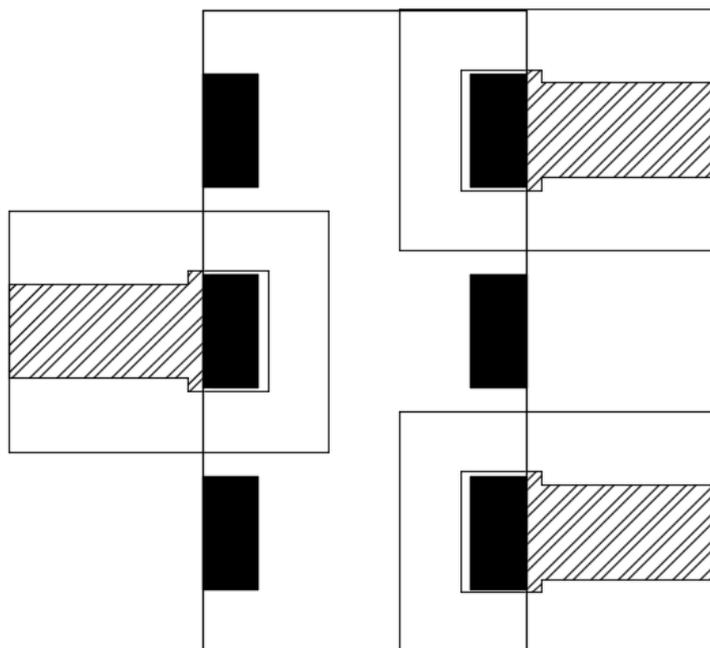


| PIN | Connection | PIN | Connection |
|-----|------------|-----|------------|
| 1   | GND        | 4   | High-band  |
| 2   | Common     | 5   | GND        |
| 3   | GND        | 6   | Low-band   |

### Dimensions

| Figure   | Symbol | Dimension (mm)  |
|--|--------|-----------------|
|  <p>The figure contains four technical drawings: 1. Top View: Shows a rectangular package with a central square pad and six surrounding pads. Dimensions L (length), W (width), and A (height) are indicated. 2. Side View: Shows the profile of the package with dimension T (thickness). 3. Bottom View: Shows the underside of the package with three pads, each having a width dimension B. 4. Top View: Shows the package with six pads numbered 1 through 6.</p> | L      | $3.2 \pm 0.10$  |
|  | W      | $1.6 \pm 0.10$  |
|  | T      | $0.9 \pm 0.10$  |
|  | A      | $0.30 \pm 0.10$ |
|  | B      | $0.56 \pm 0.10$ |
|  | C      | $1.00 \pm 0.10$ |

### Mounting Considerations



### Typical Electrical Characteristics (T=25°C)

